

Docket No. 520,431,19X00

Serial No. 10/659,372

Office Action dated December 1, 2005**AMENDMENTS TO THE SPECIFICATION**

Please amend the Specification as follows:

Page 9, please replace the paragraph beginning on line 22, with the following amended paragraph as follows:

In the vicinity of the recording/reproducing elements is formed a heating device 4 of resistor element, which is formed with a thin film, with using the thin-film process. In the present embodiment, a thin wire, such as, of permalloy, as a material of the thin-film resistor, for example, being 0.5 mm in thickness and 3 μm in width, is wound around within an area of 60 μm in width, and buried with alumina in gaps therebetween, thereby forming a heat generating body. The resistance value thereof is about 50. The heating device 4 is shown in Fig. 12, which is a view from the outflow end (i.e., the ~~Y-Y~~Z-Z cross-section in Fig. 3).